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Ohsawa et al.

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(54) **GROOVES FORMED AROUND A SEMICONDUCTOR DEVICE ON A CIRCUIT BOARD**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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Apr. 13, 2005 (JP) 2005-010992
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(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182, D13/158–177; 336/200; 324/754; D1/106; D19/10; 361/813
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for grooves formed around a semiconductor device on a circuit board, as shown and described.

DESCRIPTION

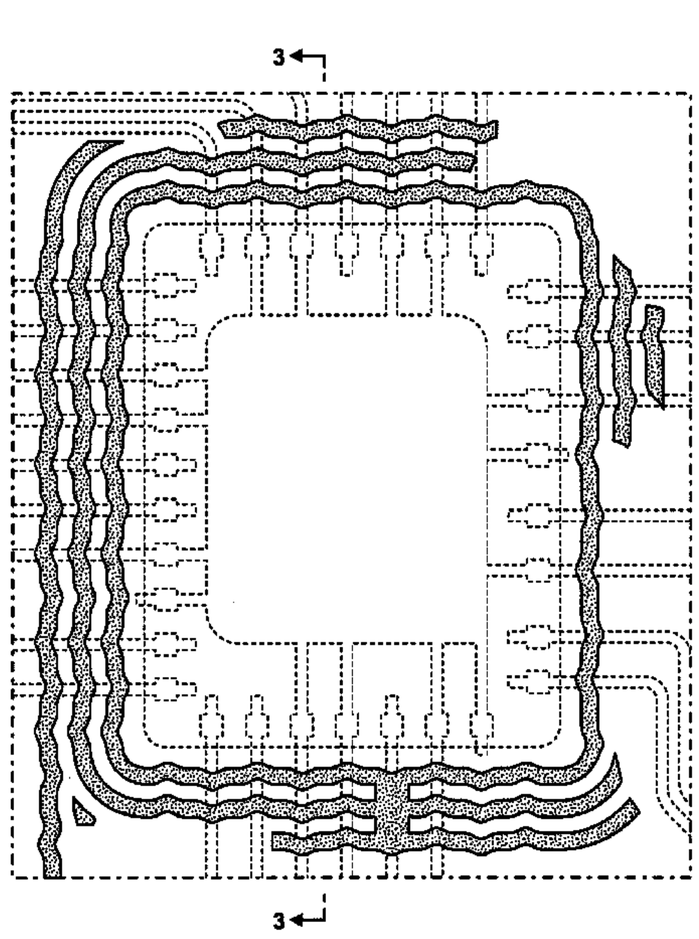
FIG. **1** shows a plan view of grooves formed around a semiconductor device on a circuit board showing our new design.

FIG. **2** shows an enlarged view of the claimed portion identified by the dot-dash line in FIG. **1**; and,

FIG. **3** shows an enlarged sectional view along the line **3**—**3** in FIG. **2**.

The special dot-dash broken line defines the boundary of the claimed design; the gray stippling indicates the surface of the groove bed; the broken lines show environmental detail for illustrative purposes only and form no part of the claimed design.

1 Claim, 3 Drawing Sheets



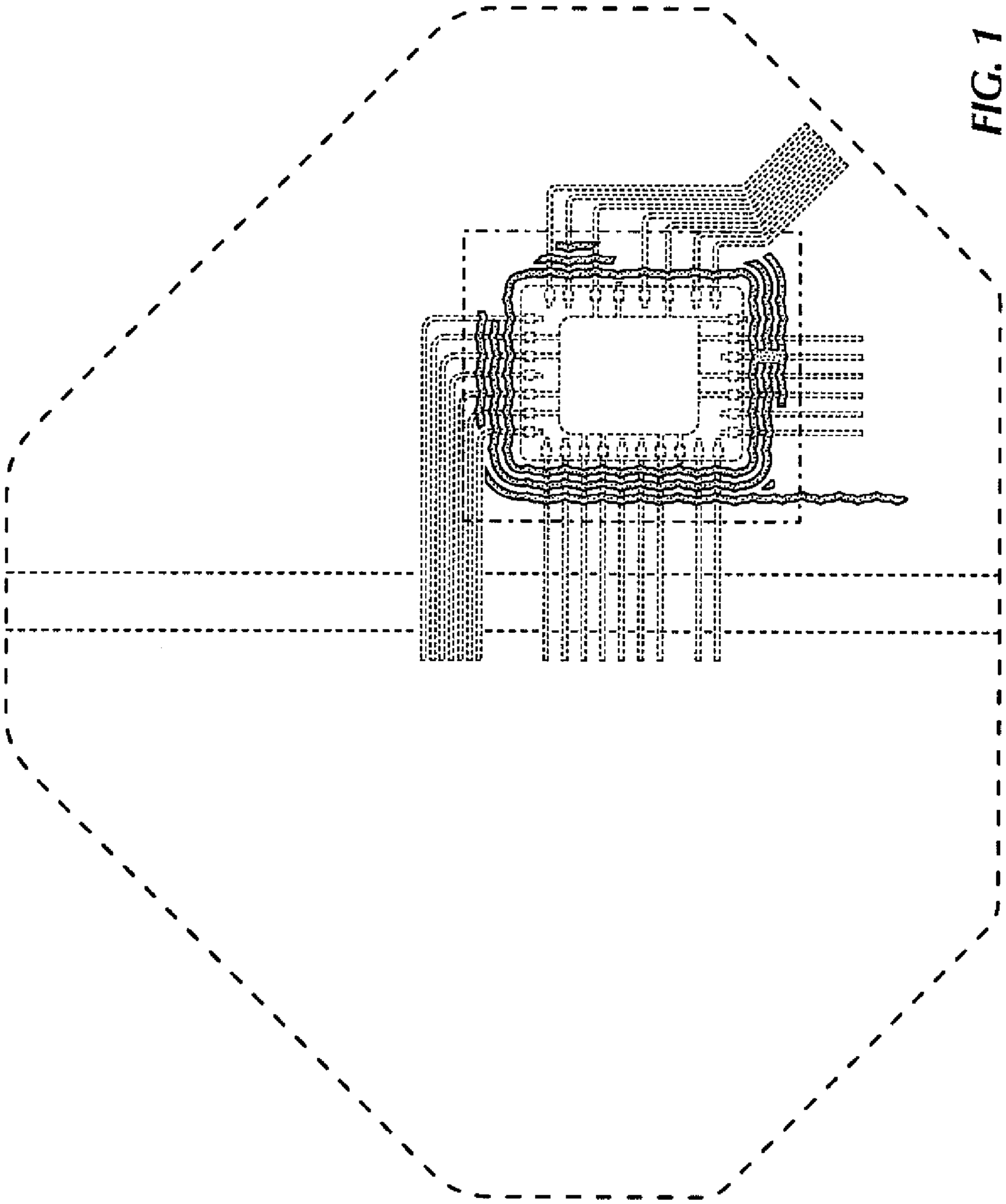


FIG. 1

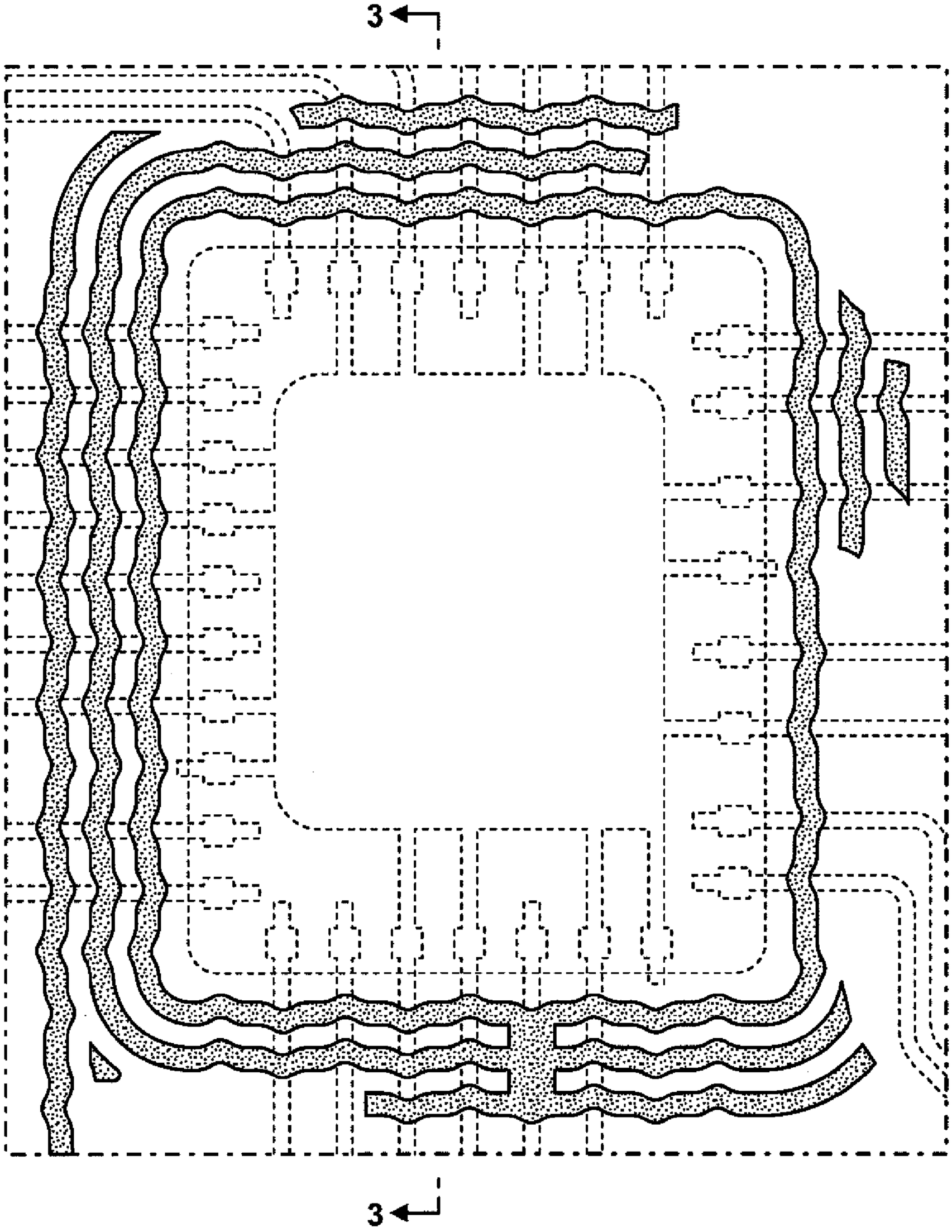


FIG. 2

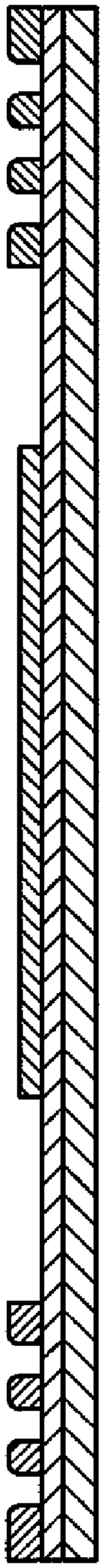


FIG. 3